# EP3600TS-75.000M

Solderability

Vibration

**Temperature Cycling** 



EP36 00

Series -RoHS Compliant (Pb-free) 3.3V 4 Pad 3.2mm x 5mm Ceramic SMD LVCMOS Programmable Oscillator

Frequency Tolerance/Stability ±100ppm Maximum

TS -75.000M Nominal Frequency

75.000MHz

Pin 1 Connection

Tri-State (Disabled Output: High Impedance) 

Operating Temperature Range 0°C to +70°C

MIL-STD-883, Method 2003

MIL-STD-883, MEthod 1010

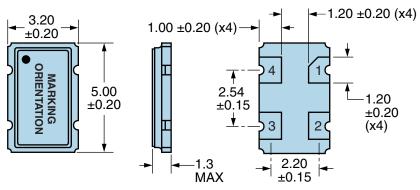
MIL-STD-883, Method 2007, Condition A

Duty	0,010
50 ±1	0(%)

ELECTRICAL SPECIFICA	
Nominal Frequency	75.000MHz
Frequency Tolerance/Stability	±100ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range,Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
Aging at 25°C	±5ppm/year Maximum
Operating Temperature Range	0°C to +70°C
Supply Voltage	3.3Vdc ±0.3Vdc
Input Current	28mA Maximum (Unloaded)
Output Voltage Logic High (Voh)	Vdd-0.4Vdc Minimum (IOH = -8mA)
Output Voltage Logic Low (Vol)	0.4Vdc Maximum (IOL = +8mA)
Rise/Fall Time	4nSec Maximum (Measured at 20% to 80% of waveform)
Duty Cycle	$50 \pm 10(\%)$ (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (Disabled Output: High Impedance)
Tri-State Input Voltage (Vih and Vil)	70% of Vdd Minimum to enable output, 20% of Vdd Maximum to disable output, No Connect to enable output.
Standby Current	20µA Maximum (Pin 1 = Ground)
Disable Current	16mA Maximum (Pin 1 = Ground)
Absolute Clock Jitter	±125pSec Maximum, ±75pSec Typical
One Sigma Clock Period Jitter	±40pSec Maximum
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C
ENVIRONMENTAL & MEC	HANICAL SPECIFICATIONS
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215

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### **MECHANICAL DIMENSIONS (all dimensions in millimeters)**



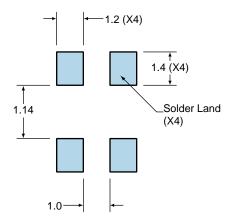
PIN	CONNECTION
1	Tri-State (High Impedance)
2	Ground/Case Ground
3	Output
4	Supply Voltage
LINE	MARKING
1	<b>E75.000</b> <i>E=Ecliptek Designator</i>

**CORPORATION** 

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#### Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

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#### **OUTPUT WAVEFORM & TIMING DIAGRAM**



**Test Circuit for CMOS Output** 



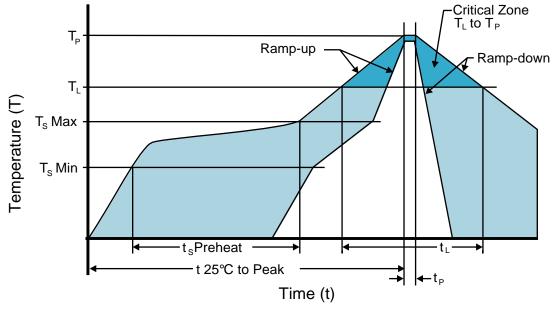
Note 1: An external  $0.1\mu$ F low frequency tantalum bypass capacitor in parallel with a  $0.01\mu$ F high frequency ceramic bypass capacitor close to the package ground and V<sub>DD</sub> pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value  $\dot{C}_L$  includes sum of all probe and fixture capacitance.

## **ECLIPTEK** CORPORATION

## **Recommended Solder Reflow Methods**



### **High Temperature Infrared/Convection**

EP3600TS-75.000M

T <sub>s</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	3°C/second Maximum
Preheat	
- Temperature Minimum (T <sub>s</sub> MIN)	150°C
<ul> <li>Temperature Typical (T<sub>s</sub> TYP)</li> </ul>	175°C
<ul> <li>Temperature Maximum (T<sub>s</sub> MAX)</li> </ul>	200°C
- Time (t <sub>s</sub> MIN)	60 - 180 Seconds
Ramp-up Rate (T⊾ to T <sub>P</sub> )	3°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	217°C
- Time (t∟)	60 - 150 Seconds
Peak Temperature (T <sub>P</sub> )	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (T <sub>P</sub> Target)	250°C +0/-5°C
Time within 5°C of actual peak (t <sub>P</sub> )	20 - 40 seconds
Ramp-down Rate	6°C/second Maximum
Time 25°C to Peak Temperature (t)	8 minutes Maximum
Moisture Sensitivity Level	Level 1

## **ECLIPTEK** CORPORATION

## **Recommended Solder Reflow Methods**

EP3600TS-75.000M



### Low Temperature Infrared/Convection 240°C

T <sub>s</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (T <sub>s</sub> TYP)	150°C
- Temperature Maximum (T <sub>s</sub> MAX)	N/A
- Time (t <sub>s</sub> MIN)	60 - 120 Seconds
Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )	5°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	150°C
- Time (t∟)	200 Seconds Maximum
Peak Temperature (T <sub>P</sub> )	240°C Maximum
Target Peak Temperature (T <sub>P</sub> Target)	240°C Maximum 1 Time / 230°C Maximum 2 Times
Time within 5°C of actual peak (t <sub>p</sub> )	10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

#### Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

#### **High Temperature Manual Soldering**

260°C Maximum for 5 seconds Maximum, 2 times Maximum.